

#### **Features**

- 1.2kV Schottky Rectifier
- Zero Reverse Recovery Current
- High-Frequency Operation
- Temperature-Independent Switching
- **Extremely Fast Switching**
- Positive Temperature Coefficient on V<sub>F</sub>

#### **Benefits**

- Replace Bipolar with Unipolar Rectifiers
- Essentially No Switching Losses
- Higher Efficiency
- Reduction of Heat Sink Requirements
- Parallel Devices Without Thermal Runaway

## **Applications**

- Switch Mode Power Supplies (SMPS)
- Boost diodes in PFC or DC/DC stages
- Free Wheeling Diodes in Inverter stages
- AC/DC converters

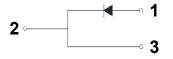
HIDH08G120C5XKSA1





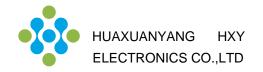
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**Maximum Ratings** (T<sub>c</sub>=25°C unless otherwise specified)

Symbol	Parameter	Value	Unit	Test Conditions	Note
$V_{RRM}$	Repetitive Peak Reverse Voltage	1200	V		
$V_{RSM}$	Surge Peak Reverse Voltage	1300	V		
V <sub>R</sub>	DC Peak Reverse Voltage	1200	V		
I <sub>F</sub>	Continuous Forward Current	24.5 12 8	А	T <sub>c</sub> =25°C T <sub>c</sub> =135°C T <sub>c</sub> =157°C	Fig. 3
I <sub>FRM</sub>	Repetitive Peak Forward Surge Current	37.5 25	А	T <sub>c</sub> =25°C, t <sub>p</sub> =10 ms, Half Sine Pulse T <sub>c</sub> =110°C, t <sub>p</sub> =10 ms, Half Sine Pulse	
I <sub>FSM</sub>	Non-Repetitive Forward Surge Current	64 49.5	А	T <sub>c</sub> =25°C, t <sub>p</sub> =10 ms, Half Sine Pulse T <sub>c</sub> =110°C, t <sub>p</sub> =10 ms, Half Sine Pulse	Fig. 8
I <sub>F,Max</sub>	Non-Repetitive Peak Forward Current	600 480	А	T <sub>c</sub> =25°C, t <sub>p</sub> =10 ms, Pulse T <sub>c</sub> =110°C, t <sub>p</sub> =10 ms, Pulse	Fig. 8
P <sub>tot</sub>	Power Dissipation	136.5 59	W	T <sub>c</sub> =25°C T <sub>c</sub> =110°C	Fig. 4
dV/dt	Diode dV/dt ruggedness	200	V/ns	V <sub>R</sub> =0-960V	
∫i²dt	i²t value	20.5 12.25	A²s	T <sub>c</sub> =25°C, t <sub>p</sub> =10 ms T <sub>c</sub> =110°C, t <sub>p</sub> =10 ms	
T <sub>J</sub>	Operating Junction Range	-55 to +175	°C		
$T_{stg}$	Storage Temperature Range	-55 to +135	°C		
	TO-220 Mounting Torque	1 8.8	Nm lbf-in	M3 Screw 6-32 Screw	



## **Electrical Characteristics**

Symbol	Parameter	Тур.	Max.	Unit	Test Conditions	Note
V <sub>F</sub>	Forward Voltage	1.5 2.2	1.8 3	V	I <sub>F</sub> = 8 A T <sub>J</sub> =25°C I <sub>F</sub> = 8 A T <sub>J</sub> =175°C	Fig. 1
I <sub>R</sub>	Reverse Current	35 100	250 350	μΑ	V <sub>R</sub> = 1200 V T <sub>J</sub> =25°C V <sub>R</sub> = 1200 V T <sub>J</sub> =175°C	Fig. 2
Q <sub>c</sub>	Total Capacitive Charge	37		nC	$V_R = 800 \text{ V, } I_F = 8 \text{ A}$ $di/dt = 200 \text{ A/}\mu\text{s}$ $T_J = 25^{\circ}\text{C}$	Fig. 5
С	Total Capacitance	560 37 27		pF	V <sub>R</sub> = 0 V, T <sub>J</sub> = 25°C, f = 1 MHz V <sub>R</sub> = 400 V, T <sub>J</sub> = 25°C, f = 1 MHz V <sub>R</sub> = 800 V, T <sub>J</sub> = 25°C, f = 1 MHz	Fig. 6
E <sub>c</sub>	Capacitance Stored Energy	10.5		μJ	V <sub>R</sub> = 800 V	Fig. 7

Note:This is a majority carrier diode, so there is no reverse recovery charge.

## **Thermal Characteristics**

Symbol	Parameter	Тур.	Unit	Note
R <sub>eJC</sub>	Thermal Resistance from Junction to Case	1.1	°C/W	Fig. 9

## **Typical Performance**

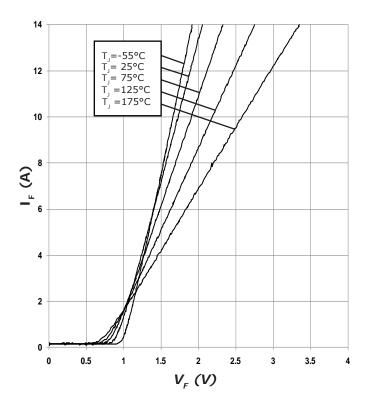


Figure 1. Forward Characteristics

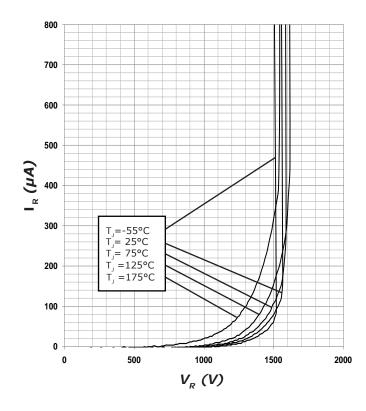
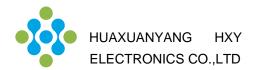
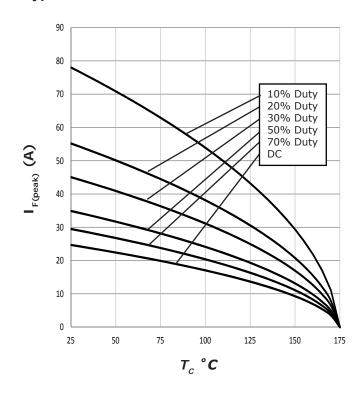


Figure 2. Reverse Characteristics



## **Typical Performance**



 $P_{Tot}$  (W) **T**<sub>c</sub> °**C** 

Figure 3. Current Derating

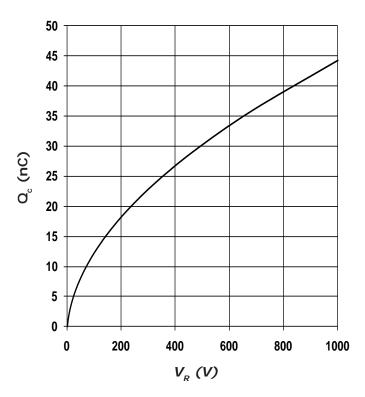


Figure 4. Power Derating

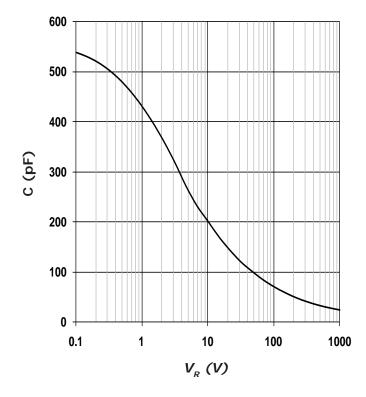
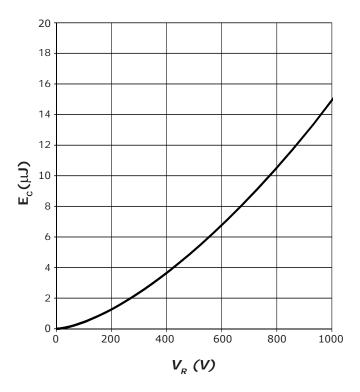


Figure 5. Recovery Charge vs. Reverse Voltage

Figure 6. Capacitance vs. Reverse Voltage



## **Typical Performance**



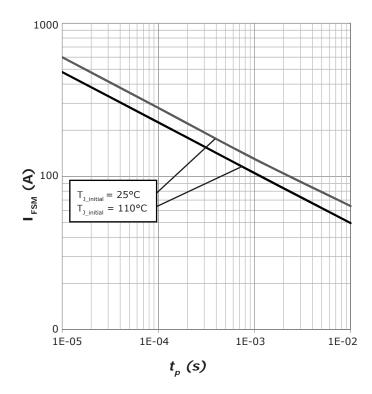


Figure 7. Typical Capacitance Stored Energy

Figure 8. Non-repetitive peak forward surge current versus pulse duration (sinusoidal waveform)

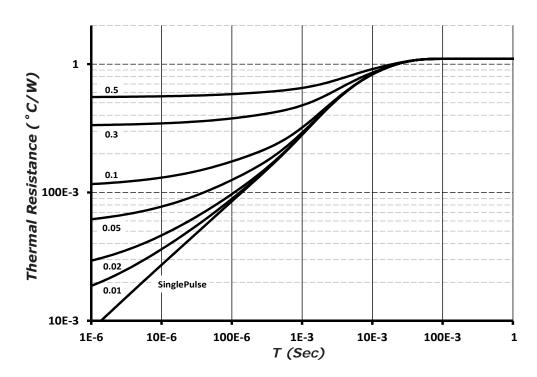
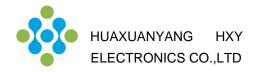


Figure 9. Transient Thermal Impedance



## **Diode Model**

$$\begin{array}{c|c} - & & \\ \hline V_T & R_T \end{array}$$

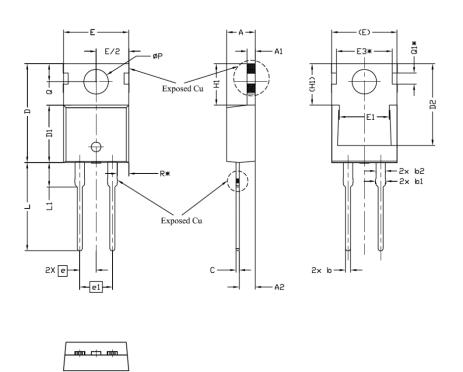
$$V_{fT} = V_T + If *R$$

$$V_T = 0.96 + (T_J^* -2.1^*10^{-3})$$
  
 $R_T = 0.06 + (T_J^* 8.0^*10^{-4})$ 

Note:  $T_j$  = Diode Junction Temperature In Degrees Celsius, valid from 25°C to 175°C

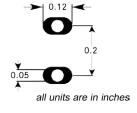


# Package Information TO-220C-2L



6) // ID 61				
SYMBOL	MIN.	NOM.	MAX.	NOTES
Α	4,24	4,44	4,64	
A1	1.15	1.27	1.40	
A2	2.30	2.48	2.70	
ь	0.70	0.80	0.90	
b1	1.20	1.55	1.75	
b2	1.20	1.45	1.70	
С	0.40	0.50	0.60	
D	14.70	15.37	16.00	4
D1	8.82	8.92	9.02	
D2	12.43	12.73	12.83	5
E	9.96	10.16	10.36	4,5
E1	6,86	7,77	8.89	5
E3*	8.70REF.			
e	2.54BSC			
e1	5.08BSC			
H1	6.30	6.45	6.60	5,6
L	13,47	13.72	13.97	
L1	3.60	3.80	4.00	
ØP	3,75	3.84	3.93	
Q	2,60	2.60 2.80		
Q1*	1,73REF.			
R*				

# **Recommended Solder Pad Layout**



TO-220C-2L

## HIDH08G120C5XKSA1

Silicon Carbide Schottky Diode

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